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	Title: Quality Pledge on Non-Use of Hazardous Banned Substances in Products		

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1 Purpose and Scope

The purpose of this document is to outline Silicon Image's Environmental and RoHS guidelines as required by the RoHS / WEEE Directives.

2 Reference Documents

The following internal documents are referenced in this procedure to define their interaction with this process:

2.1 RoHS Directive

2.2 WEEE Directive

3 Terms and Definitions

Our QMS uses the same internationally recognized terms, vocabulary and definitions given in ISO 9000:2000. ISO 9000:2000 (paragraph 3.7.2) defines documentation as "information and its supporting medium" and states that "documents" include specifications, quality manuals, quality plans, records, and procedure documents. The medium can be paper, magnetic, electronic or optical computer disc, photograph, film, or master sample, or a combination thereof.

3.1 Abbreviations and Acronyms definition


4 Control and Maintenance

The Quality / Reliability Manager/Director has overall responsibility for the maintenance of this procedure and any other related forms, flows, checklist and work instructions.

4.1 Required Approvers

All proposed major changes require the approval of the:

- Quality / Reliability Manager / Director

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All minor changes requires the approval only of the

- Quality / Reliability Manager / Director


5 Environmental Aspects

5.1 Silicon Image products are produced using wafer foundries and facilities for assembly and tests that are well-established. Processes used by our manufacturers are consistent with worker safety, responsible environmental management, and product reliability. Each foundry and facility is in compliance with ISO14001 and Silicon Image continues to monitor their environmental activities. Because of the following statements, Silicon Image self-asserts that it is in compliance with ISO14001.

6 Pledge on Non-use or Restriction of Certain Hazardous Substances in Products

6.1 In 2004, Silicon Image began the process of converting its products to be made so as not to contain or so as to limit hazardous substances as restricted by the European Union (EU), Restriction of Hazardous Substances (RoHS) Directive. Our program was also developed in support of the EU Waste of Electrical and Electronic Equipment (WEEE) directive. We have undertaken the qualification of RoHS-compliant components obtained from our suppliers and the implementation of new manufacturing processes related to this program. At this time, Silicon Image integrated circuit products that are composed of materials below levels described by the RoHS directive are available in “Green” or “Universal” packages, identified with a “G” or a “U” respectively, in their part number. All Silicon Image products and packaging materials are now RoHS-compliant as of July 1, 2006. Silicon Image has developed further procedures to eliminate the presence of other substances in addition to those restricted by the EU.

6.2 Silicon Image manages its subcontracted manufacturing service providers and declares the hazardous substances listed below are prohibited (or are limited based on the limits set below) in our Universal / Green product offerings consistent with the EU RoHS and WEEE directives and certain other sound environmental management practices.

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Cadmium and its compounds *	Lead and its compounds *
Mercury and its compounds *	Hexavalent chromium and its compounds*
Brominated organic compounds	Chlorinated paraffins (Chlorine flame retarding materials / plasticizers)
PBB (Polybromobiphenyl) category and PBDE (Polybrominatedbiphenyl ethers) including DecaBDE category*	TBBP-A-bis(Tetrabromobisphenol-A-bis(2,3-dibromopropylether))
Polychlorinated biphenyls (PCB) category	Polychlorinated naphthalene category
Organic Tin compounds (Tributhyltin category / Triphenyltin category)	Asbestos
Azo compounds	Mirex (Perchlordecone)
Ethyleneglycol ethers	Ozone depleting substances
Heavy metals in Packing materials	Halogens (Chlorine and Bromine)
PFOS (Perfluorooctane Sulfonates) *	

* Substances marked with an asterisk (*) are limited to the allowable content as outlined below per the RoHS directive:

Lead (Pb) <1000 PPM

Mercury (Hg) < 1000 PPM

Cadmium (Cd) < 100 PPM

Hexavalent chromium (CR6+) <1000 PPM

Flame retardants PBB (Polybrominated biphenyls) and PBDE (polybrominated diphenyl ethers) and DecaBDE < 1000 PPM

Halogens: Chlorine 900 ppm maximum Bromine: 900 ppm maximum (total combined not to exceed 1500 ppm)

PFOS (Perfluorooctane Sulfonates) < 1000 PPM

REVISION HISTORY

REV.	DATE	ECN	TYPE	ORIGINATOR	DESCRIPTION
A00	11/30/2007		INI		Initial release
B00	04/25/2008		Major		Added PFOS and Halogen to substance list
C00	06/20/2008		Major		Added DecaBDE